

Vishay Siliconix

P-Channel 100 V (D-S) MOSFET

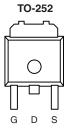
PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)		
- 100	0.195 at V _{GS} = - 10 V	- 8.8	11.7		
- 100	0.210 at V _{GS} = - 4.5 V	- 8.5	11.7		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

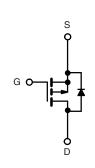
- Power Switch
- DC/DC Converters



Drain Connected to Tab

Top View

Ordering Information: SUD09P10-195-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel	MOSFET

ABSOLUTE MAXIMUM RATINGS	$T_{\rm C} = 25 ^{\circ}{\rm C}$, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	- 100	v	
Gate-Source Voltage		V _{GS}	± 20	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 25 °C		- 8.8	
Continuous Drain Current $(T_j = 150 \text{ C})$	T _C = 70 °C	I _D	- 7.1	•
Pulsed Drain Current		I _{DM}	- 15	- A
Avalanche Current		I _{AS}	- 18	
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	16.2	mJ
	T _C = 25 °C	P	32.1 ^b	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	- P _D -	2.5	- W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	50	°C/W		
Junction-to-Case (Drain)	R _{thJC}	3.9	0/10		

Notes:

a. Duty cycle ≤ 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		· · · · · ·					
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = -250 \mu A$	- 100			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 2.5	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA	
		$V_{DS} = -100 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 100 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	μΑ	
		V_{DS} = - 100 V, V_{GS} = 0 V, T_{J} = 150 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 10 V, V_{GS} = - 10 V	- 15			А	
	Б	V _{GS} = - 10 V, I _D = - 3.6 A		0.162	0.195	0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 3.4 A		0.175	0.210	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 3.6 A		12		S	
Dynamic ^b	•	·		•			
Input Capacitance	C _{iss}			1055		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 50 V, f = 1 MHz		65			
Reverse Transfer Capacitance	C _{rss}			41			
Tatal Oata Obarra ⁶	0	$V_{DS} = -50 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -3.6 \text{ A}$		23.2	34.8	nC	
Total Gate Charge ^c	Qg			11.7	17.6		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = - 50 V, V_{GS} = - 4.5 V, I_{D} = - 3.6 A		3.5			
Gate-Drain Charge ^c	Q _{gd}			4.8			
Gate Resistance	Rg	f = 1 MHz	1.2	5.7	11.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			7	14		
Rise Time ^c	t _r	V_{DD} = - 50 V, R_L = 17.2 Ω		12	18	20	
Turn-Off Delay Time ^c	t _{d(off)}	$I_{D} \cong$ - 2.9 A, V_{GEN} = - 10 V, R_{g} = 1 Ω		33	50	ns	
Fall Time ^c	t _f			9	18	1	
Drain-Source Body Diode Ratings an	nd Character	istics T _C = 25 °C ^b					
Continuous Current	ا _S				- 8.8		
Pulsed Current	I _{SM}				- 15	A	
Forward Voltage ^a	V _{SD}	$I_{F} = -2.9 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			50	75	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 2.9 A, dl/dt = 100 A/μs		- 4	- 6	А	
Reverse Recovery Charge	Q _{rr}	1 F		98	147	nC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

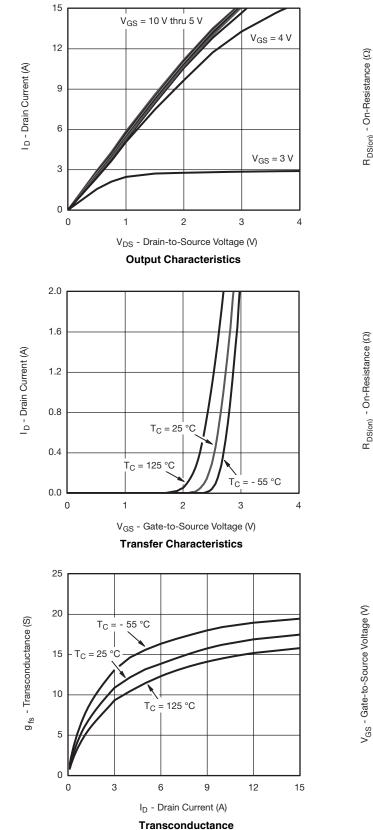
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

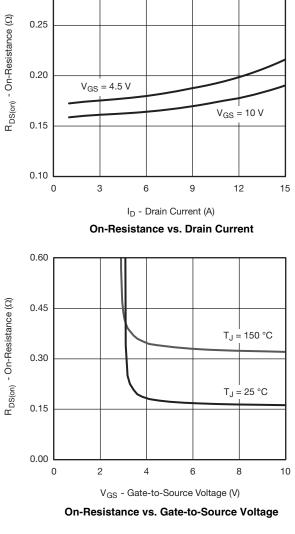


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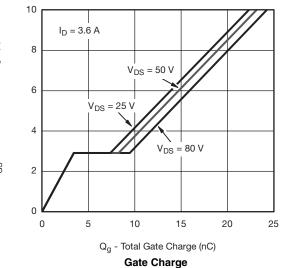
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



0.30

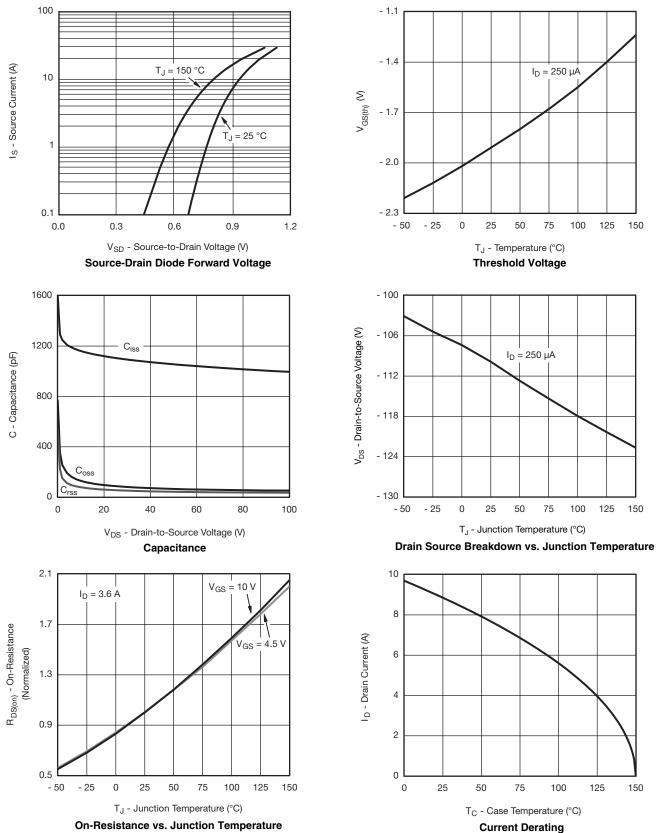


Document Number: 65903 S10-0634-Rev. A, 22-Mar-10



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



100 100 Limited by R_{DS(on)} 10 I_D - Drain Current (A) 100 µs . Т_J = 25 °С T_ = 150 °C I_{DAV} (A) 1 ms 10 1 10 ms 100 ms 1 s, 10 s, DC T_A = 25 °C 0.1 Single Pulse 111 **BVDSS** Limited 0.01 10-6 10⁻⁵ 10-2 10-4 10⁻³ 10-1 0.1 1 10 100 V_{DS} - Drain-to-Source Voltage (V) Time (s) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Single Pulse Avalanche Current Capability vs. Time Safe Operating Area 1 Normalized Effective Transient Thermal Impedance Duty Cycle = 0.5 0.2 0.1 0.05 0 02 111 Single Pulse 0.1 10-4 10⁻³ 10-2 10-1 1 10 Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

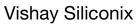
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

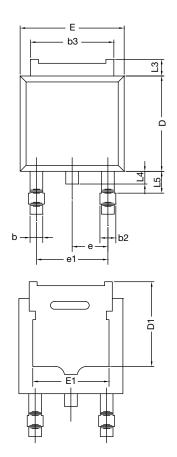
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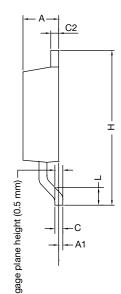
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TO-252AA Case Outline





	MILLIN	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
С	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	4.10	-	0.161	-
Е	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
Н	9.40	10.41	0.370	0.410
е	2.28 BSC		0.090 BSC	
e1	4.56	BSC	0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.01	1.52	0.040	0.060
ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347				

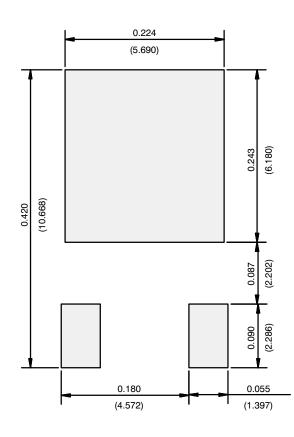
Notes

• Dimension L3 is for reference only.



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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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